

SOT1575-1

plastic thermally enhanced quad flat non-leaded package; 24 terminals; 1.0 mm pitch; 7 mm x 7 mm x 2.2 mm body

4 November 2019

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	HQFN24
Package type industry code	HQFN24
Package style descriptive code	HQFN (thermal enhanced quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	08-01-2016
Manufacturer package code	98ASA00432D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	7	-	mm
package width	-	7	-	mm
seated height	-	2.2	2.3	mm
nominal pitch	-	1	-	mm
actual quantity of termination	-	24	-	



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2 Package outline

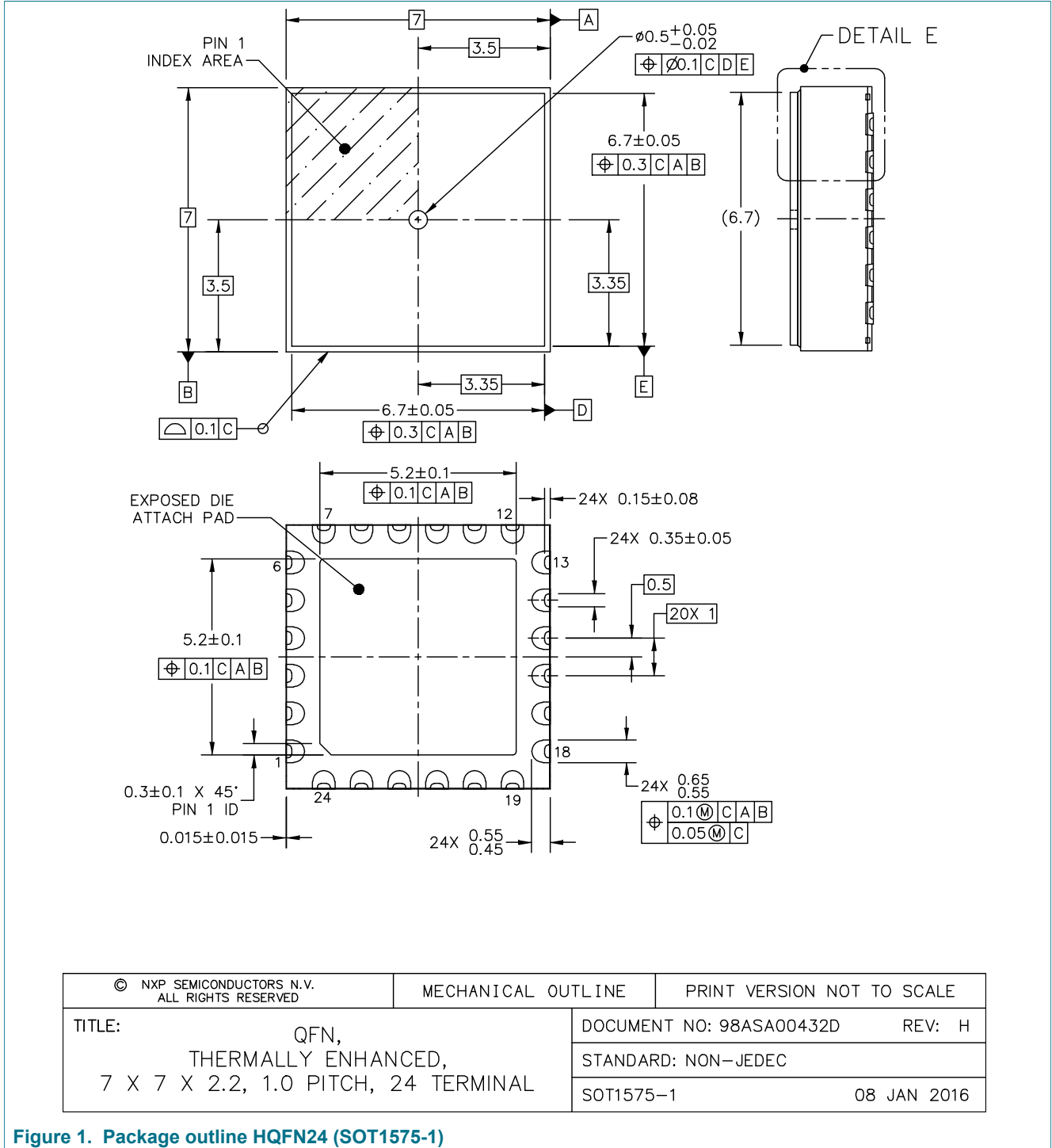


Figure 1. Package outline HQFN24 (SOT1575-1)

plastic thermally enhanced quad flat non-leaded package; 24 terminals; 1.0 mm pitch; 7 mm x 7 mm x 2.2 mm body

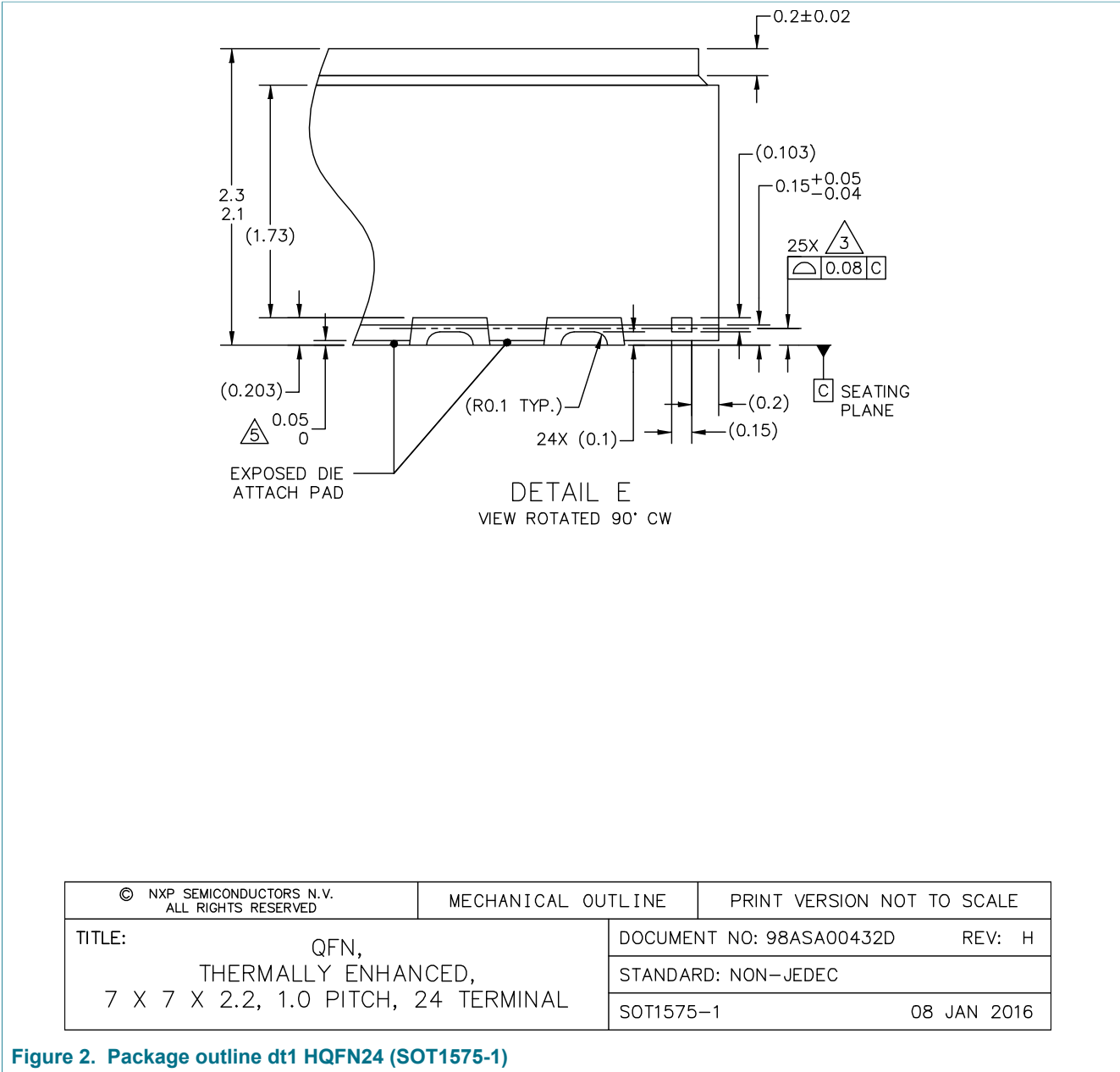


Figure 2. Package outline dt1 HQFN24 (SOT1575-1)

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NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. COPLANARITY APPLIES TO LEADS, AND DIE ATTACH PAD.
4. MIN METAL GAP SHOULD BE 0.2MM.
5. THIS DIMENSION APPLIES ONLY FOR TERMINALS.

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TITLE: QFN, THERMALLY ENHANCED, 7 X 7 X 2.2, 1.0 PITCH, 24 TERMINAL	DOCUMENT NO: 98ASA00432D	REV: H
	STANDARD: NON-JEDEC	
	SOT1575-1	08 JAN 2016

Figure 3. Package outline note HQFN24 (SOT1575-1)

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3 Legal information

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